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a pair of electrodes or electrode groups; and

5 a plurality of capacitor terminals, wherein the respective capacitor terminals are electrically connected to one or the other of the paired electrodes or electrode groups;

the printed wiring substrate comprises a plurality of substrate terminals;

the IC chip comprises a plurality of connection-to-capacitor terminals  
and a plurality of connection-to-substrate terminals;

the plurality of capacitor terminals of the capacitor are respectively flip-chip-bonded to a plurality of connection-to-capacitor terminals of the IC chip; and

15 the plurality of substrate terminals of the printed wiring substrate are respectively flip-chip-bonded to a plurality of connection-to-substrate terminals of the IC chip.

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3. The printed wiring substrate according to claim 2, wherein the IC-chip-carrying printed wiring substrate is a CSP adapted for mounting an IC chip.

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4. A printed wiring substrate having a built-in capacitor for mounting an IC chip or IC-chip-carrying printed wiring substrate having a plurality of connection-to-capacitor terminals and a plurality of connection-to-substrate terminals, characterized in that:

5 the capacitor comprises:

a pair of electrodes or electrode groups; and

a plurality of capacitor terminals capable of being respectively flip-chip-bonded or bonded in a connection-face-to-connection-face manner to a plurality of connection-to-capacitor terminals of the IC chip or IC-chip-carrying printed wiring substrate, wherein the respective capacitor terminals are electrically connected to one or the other of the paired electrodes or electrode groups; and

the printed wiring substrate comprises a plurality of substrate terminals capable of being respectively flip-chip-bonded or bonded in a connection-face-to-connection-face manner to a plurality of connection-to-substrate terminals of the IC chip or IC-chip-carrying printed wiring substrate.

7. The printed wiring substrate according to claim 6, wherein the capacitor and the printed wiring substrate are fixed together with an insulating resin.

~~4~~ 6. The printed wiring substrate according to claim ~~4~~ 6, characterized in that:

the capacitor comprises a first capacitor main-surface, on which the plurality of capacitor terminals are formed;

5 the printed wiring substrate comprises a first substrate main-surface, on  
which the plurality of substrate terminals are formed; and

the plurality of capacitor terminals and the plurality of substrate terminals are substantially coplanar.

9. The printed wiring substrate according to claim 6, characterized in that:

the printed wiring substrate comprises:

a capacitor accommodation cavity for accommodating the capacitor;

a cavity periphery region located around the capacitor accommodation cavity; and

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The printed wiring substrate according to claim 4, characterized in that:

the printed wiring substrate comprises a capacitor accommodation cavity for accommodating the capacitor, said capacitor being disposed in the capacitor accommodation cavity; and

the capacitor accommodation cavity comprises a capacitor position restriction portion which abuts the capacitor disposed therein so as to restrict a position of the capacitor in a depth direction of the capacitor accommodation cavity.

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The printed wiring substrate according to claim 4, characterized in that:

the printed wiring substrate assumes a substantially plate shape having a first substrate main-surface and a second substrate main-surface and comprises:

a closed-bottomed capacitor accommodation cavity which is sunk below the first substrate main-surface toward the second substrate main-surface and is adapted to accommodate the capacitor;

a plurality of second-surface substrate terminals formed on the second substrate main-surface; and

a plurality of connection lines extending from some of the plurality of second-surface substrate terminals to a bottom surface of the closed-bottomed

capacitor accommodation cavity;

the capacitor is disposed in the closed-bottomed capacitor  
15 accommodation cavity and comprises:

a first capacitor main-surface;

a second capacitor main-surface substantially parallel to the first capacitor main-surface; and

a plurality of second-surface capacitor terminals formed on the second  
20 capacitor main-surface, wherein the respective second-surface capacitor  
terminals are electrically connected to one or the other of the paired electrodes  
or electrode groups;

the plurality of substrate terminals are formed on the first substrate main-surface;

the plurality of capacitor terminals are formed on the first capacitor  
main-surface; and

the plurality of second-surface capacitor terminals are connected to corresponding connection lines which extend to the bottom surface of the closed-bottomed capacitor accommodation cavity.

12/10. The wiring substrate according to claim 4, characterized in that:

the printed wiring substrate assumes a substantially plate shape having a first substrate main-surface and a second substrate main-surface and



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11. The printed wiring substrate according to claim 9, wherein the plurality of second-surface capacitor terminals are disposed at intervals greater than those of the plurality of capacitor terminals.

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~~19~~ 12. The printed wiring substrate according to claim ~~10~~, wherein the plurality of second-surface capacitor terminals are disposed at intervals greater than those of the plurality of capacitor terminals.

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13. The printed wiring substrate according to claim 4, wherein the printed wiring substrate serves as an interposer between the IC-chip-carrying printed wiring substrate and another printed wiring substrate.

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14. A printed wiring substrate for connection to an IC chip or IC-chip-carrying printed wiring substrate, said IC chip or IC-chip-carrying printed wiring substrate comprising a plurality of connection-to-capacitor terminals for connection to a capacitor and a plurality of connection-to-substrate terminals for connection to the printed wiring substrate, the printed wiring substrate comprising a plurality of substrate terminals capable of being respectively flip-chip-bonded or bonded in a connection-face-to-connection-face manner to the plurality of connection-to-substrate terminals of the IC chip or IC-chip-carrying printed wiring substrate.

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15. A capacitor for connection to an IC chip or IC-chip-carrying printed wiring substrate, said IC chip or IC-chip-carrying printed wiring substrate comprising a plurality of connection-to-capacitor terminals for

2. A printed wiring substrate having a built-in capacitor on which an IC-chip-carrying printed wiring substrate is mounted, characterized in that:

the capacitor comprises:

a pair of electrodes or electrode groups; and

5 a plurality of capacitor terminals, wherein the respective capacitor terminals are electrically connected to one or the other of the paired electrodes or electrode groups;

the printed wiring substrate comprises a plurality of substrate terminals;

10 the IC chip-carrying printed wiring circuit comprises a plurality of connection-to-capacitor terminals and a plurality of connection-to-substrate terminals;

the plurality of capacitor terminals of the capacitor are respectively bonded in a connection-face-to-connection-face manner to a plurality of  
15 connection-to-capacitor terminals of the IC-chip-carrying printed wiring substrate; and

the plurality of substrate terminals of the printed wiring substrate are respectively bonded in a connection-face-to-connection-face manner to a plurality of connection-to-substrate terminals of the IC-chip-carrying printed  
20 wiring substrate.



connection to the capacitor and a plurality of connection-to-substrate terminals

5 for connection to a printed wiring substrate, the capacitor comprising:

a pair of electrodes or electrode groups; and

a plurality of capacitor terminals capable of being respectively flip-chip-bonded or bonded in a connection-face-to-connection-face manner to the plurality of connection-to-capacitor terminals of the IC chip or IC-chip-carrying printed wiring substrate, wherein the respective capacitor terminals are electrically connected to one or the other of the paired electrodes or electrode groups.

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